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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception
- Balanced Propagation Delays
- ±24-mA Output Drive Current
   Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

#### description/ordering information

The 'AC138 decoders/demultiplexers are designed for high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications (see Application Information).

ТА	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC138E	CD74AC138E
–55°C to 125°C	SOIC – M	Tube	CD74AC138M	AC138M
-55 C 10 125 C	301C - M	Tape and reel	CD74AC138M96	ACTSON
	CDIP – F	Tube	CD54AC138F3A	CD54AC138F3A

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



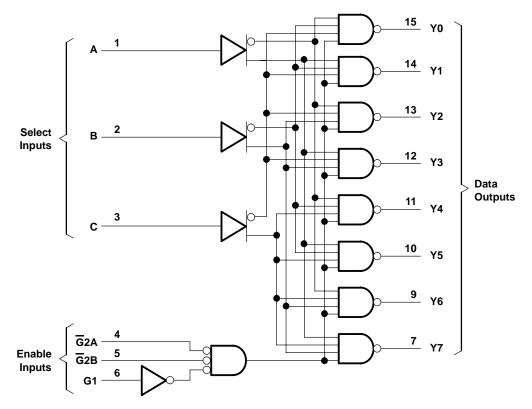
Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CD74AC138			ACKAGE /  PACKAGE )
A [	1	16	] V <sub>CC</sub>
B [	2	15	] Y0
C [	3	14	] Y1
G2A [	4	13	] Y2
G2B [	5	12	] Y3
G1 [	6	11	] Y4
Y7 [	7	10	] Y5
GND [	8	9	] Y6

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					F	UNCTIO	N TABL	E					
ENA	BLE INF	PUTS	SEL	ECT INF	UTS				OUT	PUTS			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
х	Х	н	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
L	х	х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	н	н	L	Н	Н	Н	Н	Н	н
н	L	L	L	Н	L	н	Н	L	Н	Н	Н	Н	н
н	L	L	L	Н	н	н	Н	Н	L	Н	Н	Н	н
н	L	L	н	L	L	н	Н	Н	Н	L	Н	Н	н
н	L	L	н	L	Н	н	Н	Н	Н	Н	L	Н	Н
н	L	L	н	Н	L	н	Н	Н	Н	н	Н	L	Н
н	L	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	L

### logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, I <sub>IK</sub> (VI < 0 V or VI > V <sub>CC</sub> ) (see Note 1)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	
M package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

			T <sub>A</sub> =	25°C	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
VIН	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA
IOL	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		24		24		24	mA
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V		50		50		50	ns/V
ΔυΔν	Input transition rise or fall rate	$V_{CC}$ = 3.6 V to 5.5 V		20		20		20	115/ V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS	Vcc	T <sub>A</sub> = 2	25°C	–55°( 125		–40°( 85°		UNIT
					MAX	MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		1.4		
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		
		I <sub>OH</sub> = -50 mA†	5.5 V			3.85				
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65		-	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65	
Ц	$V_{I} = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or GND},$	IO = 0	5.5 V		8		160		80	μA
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

## switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$ , $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C 85°(		UNIT
		(001F01)	MIN M	IAX	MIN	MAX	
<sup>t</sup> PLH	A, B, C	Any Y		138		125	ns
<sup>t</sup> PHL	А, В, С	Ally I		138		125	115
<sup>t</sup> PLH	64	Any Y		138		125	ns
<sup>t</sup> PHL	G1	Ally I		138		125	115
<sup>t</sup> PLH	G2A, G2B	Any Y		125		114	ns
<sup>t</sup> PHL	027, 020			125		114	112



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	–55° 125		–40° 85°	UNIT	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH		Any M	3.9	15.4	4	14	
<sup>t</sup> PHL	A, B, C	Any Y	3.9	15.4	4	14	ns
<sup>t</sup> PLH	01		3.9	15.4	4	14	200
<sup>t</sup> PHL	G1	Any Y	3.9	15.4	4	14	ns
<sup>t</sup> PLH	G2A, G2B	Any X	3.5	14	3.6	12.7	-
<sup>t</sup> PHL	GZA, GZB	Any Y	3.5	14	3.6	12.7	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

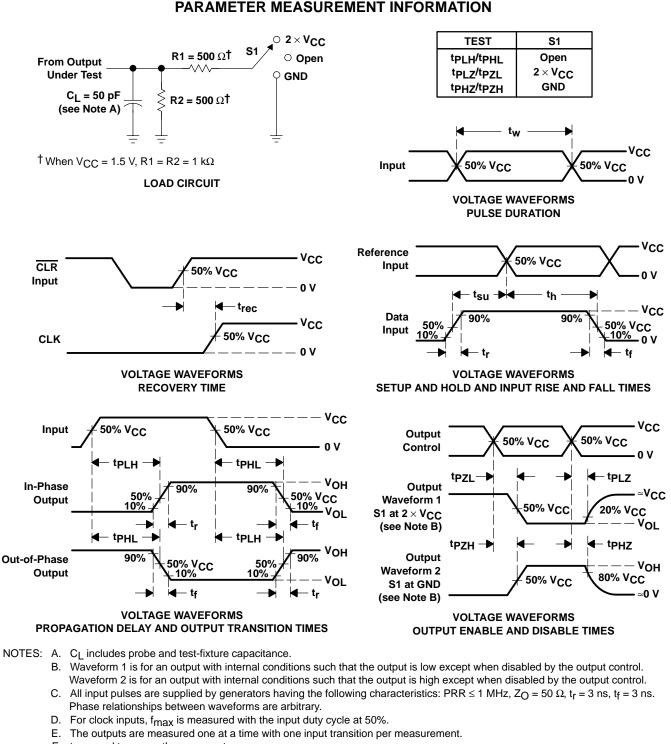
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40° 85°	UNIT	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH			2.8	11	2.8	10	ns
<sup>t</sup> PHL	A, B, C	Any Y	2.8	11	2.8	10	115
<sup>t</sup> PLH		Any Y	2.8	11	2.8	10	ns
<sup>t</sup> PHL	G1		2.8	11	2.8	10	115
<sup>t</sup> PLH	G2A, G2B		2.5	10	2.6	9.1	200
<sup>t</sup> PHL	GZA, GZB	Any Y	2.5	10	2.6	9.1	ns

#### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

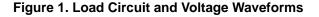
	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	110	pF



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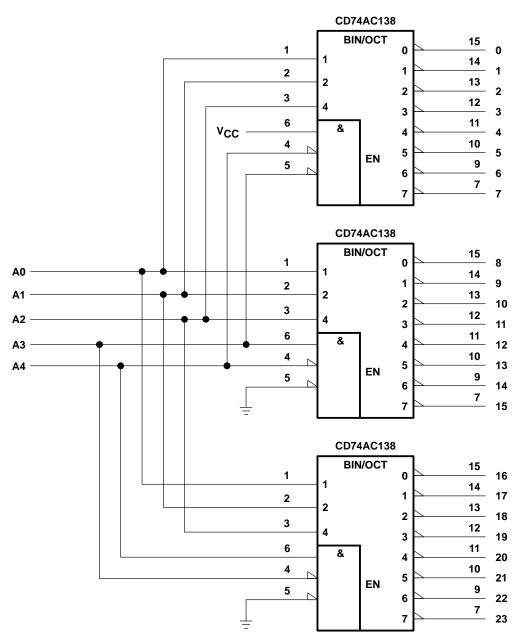


- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. tPZL and tPZH are the same as ten.
- H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- I. All parameters and waveforms are not applicable to all devices.





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**APPLICATION INFORMATION** 

Figure 2. 24-Bit Decoding Scheme



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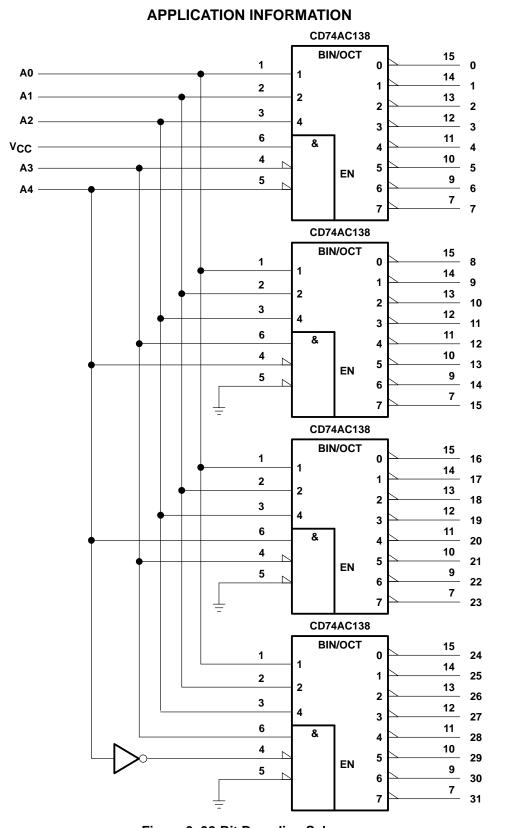


Figure 3. 32-Bit Decoding Scheme





#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CD54AC138F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC138F3A	Samples
CD74AC138E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC138E	Samples
CD74AC138EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC138E	Samples
CD74AC138M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC138M	Samples
CD74AC138M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC138M	Samples
CD74AC138ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC138M	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF CD54AC138, CD74AC138 :

- Catalog : CD74AC138
- Military : CD54AC138

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

STRUMENTS

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC138M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74AC138M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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## PACKAGE MATERIALS INFORMATION

3-Jun-2022



\*All dimensions are nominal

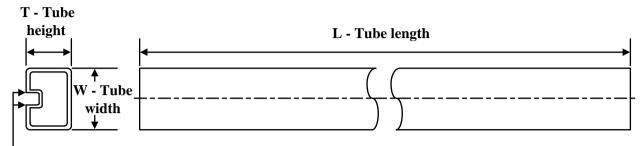
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC138M96	SOIC	D	16	2500	356.0	356.0	35.0
CD74AC138M96	SOIC	D	16	2500	340.5	336.1	32.0

#### TEXAS INSTRUMENTS

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#### TUBE



### - B - Alignment groove width

#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74AC138E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC138E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC138EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC138EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC138M	D	SOIC	16	40	506.6	8	3940	4.32
CD74AC138M	D	SOIC	16	40	507	8	3940	4.32
CD74AC138ME4	D	SOIC	16	40	506.6	8	3940	4.32
CD74AC138ME4	D	SOIC	16	40	507	8	3940	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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## D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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